+357 96 030922
info@marketpublishers.com

Global Low-Power IC Design Services Market 2026 by Company, Regions, Type and Application, Forecast to 2032

https://marketpublishers.com/r/GA2E12745B7DEN.html
Date: August 2026
Pages: 155
Price: US$ 3,480.00 (Single User License)
ID: GA2E12745B7DEN

Abstracts

According to our (Global Info Research) latest study, the global Low-Power IC Design Services market size was valued at US$ 3066 million in 2025 and is forecast to a readjusted size of US$ 5387 million by 2032 with a CAGR of 8.5% during review period.

Low-power IC design services are professional engineering services for ASIC, SoC, and custom IC development, intended to systematically reduce dynamic power, static leakage, peak current, thermal density, and system-level energy consumption under defined constraints for performance, area, cost, reliability, and time to market. These services usually begin at the specification and microarchitecture stages, where the target process, IP portfolio, software workloads, and end-product power budget are used to plan power domains, clock domains, voltage domains, power-state machines, and power-management interfaces. They then continue through RTL design, logic synthesis, power-aware simulation, formal verification, physical implementation, timing closure, IR-drop analysis, thermal analysis, DFT insertion, and signoff. Common techniques include clock gating, power gating, multi-voltage supply, dynamic voltage and frequency scaling, adaptive voltage scaling, low-leakage standard-cell library selection, memory power optimization, power-aware verification, and software-coordinated power management. Typical customers include fabless semiconductor companies, system vendors, cloud service providers, automotive electronics companies, industrial equipment companies, consumer electronics brands, and semiconductor startups. Applications cover mobile devices, IoT, wearables, edge AI, automotive electronics, data-center acceleration, wireless communications, medical electronics, and industrial control. Delivery models include low-power architecture consulting, module-level optimization, front-end to back-end implementation services, RTL-to-GDSII delivery, turnkey ASIC development, IP integration, packaging and

+357 96 030922
info@marketpublishers.com

testing coordination, and production ramp support.

The strategic value of low-power IC design services is evolving from localized power optimization into a system-level capability for chip competitiveness. As ASICs and SoCs are increasingly adopted in mobile devices, IoT, edge AI, automotive electronics, and data centers, customers no longer focus only on reducing the power consumption of individual modules. Instead, they require a continuous energy-efficiency loop across architecture, software, IP, process technology, packaging, and production ramp-up. Low-power capability must be embedded at the early specification stage through the planning of power domains, clock domains, voltage domains, power states, and software control interfaces, and must then be continuously converged through RTL, synthesis, verification, place and route, IR-drop analysis, thermal analysis, and signoff. Its commercial value lies in extending battery life, reducing thermal costs, improving chip performance per watt, lowering system failure risks, and enhancing product differentiation. For customers, the value of external low-power design services is not simply engineering capacity, but the integration of advanced-node experience, power-aware methodology, IP integration capability, and production risk control into deliverable outcomes.

The competitive landscape is becoming increasingly ecosystem-driven and regionally clustered. Taiwan, Japan, South Korea, India, mainland China, the United States, and Europe all have different types of low-power IC design service providers. Taiwanese companies have strong foundations in turnkey ASIC services, IP integration, and advanced packaging coordination. Japanese companies emphasize high-reliability SoC design and power-intent flows. Korean companies are developing design services through the Samsung Foundry ecosystem. Indian companies continue to expand in engineering outsourcing, verification, back-end design, and embedded-system collaboration. Mainland Chinese companies are building service capabilities around domestic process technologies, IoT, automotive, and custom SoCs. Competition among service providers is no longer determined only by low-cost engineering labor, but by the ability to cover the full chain from specification to GDSII, from IP to packaging and testing, and from low-power verification to production ramp-up. As chip complexity increases, suppliers that can combine advanced process technology, low-power methodology, high-speed interfaces, automotive functional safety, and AI workload optimization will gain stronger pricing power.

Future growth will be driven jointly by demand for energy-efficient computing and customized chips. AI inference is moving from cloud environments toward the edge, automotive electronics are evolving from single-function control to high-computing

+357 96 030922
info@marketpublishers.com

domain control, industrial and medical devices are upgrading from connected terminals to low-power systems with local intelligence, and cloud service providers are continuing to explore custom ASICs to improve computing efficiency per unit of energy. These trends will expand low-power design services beyond traditional smartphone and consumer electronics use cases into edge AI, smart vehicles, industrial IoT, data-center acceleration, and communications infrastructure. In terms of market size, low-power IC design services are usually embedded within ASIC design services, SoC development services, and chip design outsourcing contracts, so public statistical definitions vary. However, their growth rate is expected to exceed that of traditional general-purpose design services. As AI-assisted EDA, power-aware verification, advanced packaging, and software-coordinated power management mature, low-power design services will gradually evolve from project-based engineering services into platformized, process-driven, and ecosystem-based delivery capabilities.

This report is a detailed and comprehensive analysis for global Low-Power IC Design Services market. Both quantitative and qualitative analyses are presented by company, by region & country, by Design Task and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Low-Power IC Design Services market size and forecasts, in consumption value ($ Million), 2021-2032

Global Low-Power IC Design Services market size and forecasts by region and country, in consumption value ($ Million), 2021-2032

Global Low-Power IC Design Services market size and forecasts, by Design Task and by Application, in consumption value ($ Million), 2021-2032

Global Low-Power IC Design Services market shares of main players, in revenue ($ Million), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

+357 96 030922
info@marketpublishers.com

To assess the growth potential for Low-Power IC Design Services

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Low-Power IC Design Services market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include GUC, Socionext Inc., MegaChips Corporation, Alchip Technologies, Limited, Faraday Technology Corporation, VeriSilicon Microelectronics (Shanghai) Co., Ltd., Brite Semiconductor (Shanghai) Co., Ltd., MediaTek Inc., ADTechnology Co., Ltd., GAONCHIPS Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

Low-Power IC Design Services market is split by Design Task and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for Consumption Value by Design Task and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Design Task

Architectural Low-Power Design

RTL Low-Power Design

Power Intent Design

Power-Aware Verification

Physical Low-Power Implementation

Low-Power Signoff Optimization

+357 96 030922
info@marketpublishers.com

Low-Power Production Ramp Support

Other

Market segment by Technical Method

Clock Gating

Power Gating

Multi-Voltage Domain

Dynamic Voltage and Frequency Scaling

Adaptive Voltage Scaling

Low-Leakage Library Optimization

Memory Power Optimization

Software-Coordinated Power Management

Other

Market segment by Delivery Model

Consulting and Assessment Service

Module Design Service

Front-End and Back-End Co-Design Service

RTL-to-GDSII Service

Turnkey ASIC Service

+357 96 030922
info@marketpublishers.com

Production Support Service

Other

Market segment by Application

Mobile Devices

IoT Devices

Wearable Devices

Edge AI

Other

Market segment by players, this report covers

GUC

Socionext Inc.

MegaChips Corporation

Alchip Technologies, Limited

Faraday Technology Corporation

VeriSilicon Microelectronics (Shanghai) Co., Ltd.

Brite Semiconductor (Shanghai) Co., Ltd.

MediaTek Inc.

ADTechnology Co., Ltd.

GAONCHIPS Co., Ltd.

+357 96 030922
info@marketpublishers.com

CoAsia SEMI Co., Ltd.

Cyient Semiconductors

Tessolve Semiconductor Pvt. Ltd.

eInfochips

MosChip Technologies Limited

Sondrel (Holdings) plc

Avnet, Inc.

CoreHW Oy

eTech ASIC Inc.

Progate Group Corporation

ALi Corporation

CMSC, Inc.

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

+357 96 030922
info@marketpublishers.com

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe Low-Power IC Design Services product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Low-Power IC Design Services, with revenue, gross margin, and global market share of Low-Power IC Design Services from 2021 to 2026.

Chapter 3, the Low-Power IC Design Services competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Design Task and by Application, with consumption value and growth rate by Design Task, by Application, from 2021 to 2032.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2021 to 2026.and Low-Power IC Design Services market forecast, by regions, by Design Task and by Application, with consumption value, from 2027 to 2032.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Low-Power IC Design Services.

Chapter 13, to describe Low-Power IC Design Services research findings and conclusion.

+357 96 030922
info@marketpublishers.com

Contents

+357 96 030922
info@marketpublishers.com

2 COMPANY PROFILES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global Low-Power IC Design Services Market 2026 by Company, Regions, Type and Application, Forecast to 2032

Product link: https://marketpublishers.com/r/GA2E12745B7DEN.html

Price: US$ 3,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/GA2E12745B7DEN.html